PCN Number:	20200518002	PCN Date:	June 16, 2020		
Title: Datasheet for CD74HCU04-Q1					
Customer Contact:	PCN Manager		Dept:	Quality Services	
Change Type:					
		ign		Bump Site	
Assembly Process		Data Sheet		Wafer Bump Material	
Assembly Materials		number change		Bump Process	
Mechanical Specifi		Site		Fab Site	
Packing/Shipping/	Labeling Test	Process		Fab Materials	
			Wafer	Fab Process	
Notification Details					
Description of Change:					
Texas Instruments Incorporated is announcing an information only notification.					
The product datasheet(s) is being updated as summarized below. The following change history provides further details.					
TEXAS CD74HCU04-Q1					
INSTRUMENTS			NE 2010-REVISED APRIL 2020		
Changes from Revision (June 2010) to Revision A Page					
Updated to new data sheet standards					
Thermal impedance R _{BJA} updated from 112.6 to 121.1 °C/W					
The datasheet number will be changing.					
Device Family		Change From:	Change	Change To:	
CD74HCU04-Q1		SCHS381	SCHS3	SCHS381A	
These changes may be reviewed at the datasheet links provided.					
http://www.ti.com/product/CD74HCU04-Q1					
Reason for Change:					
To accurately reflect device characteristics.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.					
Changes to product identification resulting from this PCN:					
None.					
Product Affected:					
CD74HCH04OPWPO1					

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN www admin_team@list.ti.com

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